

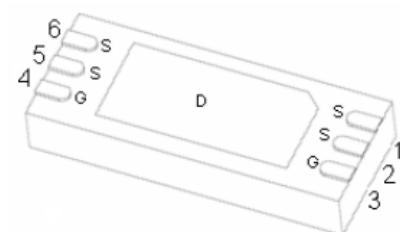
## DFNWB5×2-6L-A Plastic-Encapsulate MOSFETs

### CJND2007 Dual N-Channel MOSFET

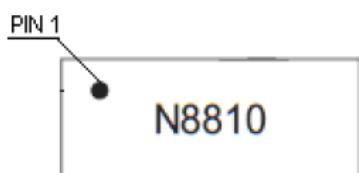
#### DESCRIPTION

The CJND2007 uses advanced trench technology to provide excellent  $R_{DS(ON)}$  and low gate charge. It is ESD protected. This device is suitable for use as a uni-directional or bi-directional load switch, facilitated by its common-drain configuration.

**DFNWB5×2-6L-A**



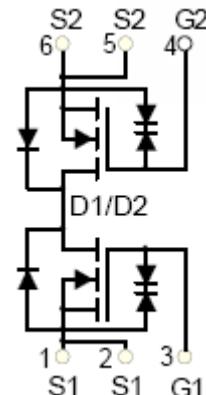
#### MARKING:



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#### MAXIMUM RATINGS ( $T_a=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Value	Unit
Drain-Source Voltage	$V_{DS}$	20	V
Gate-Source Voltage	$V_{GS}$	$\pm 12$	V
Continuous Drain Current	$I_D$	7	A
Pulsed Drain Current	$I_{DM}^*$	30	A
Thermal Resistance from Junction to Ambient(note1)	$R_{\theta JA}$	175	$^\circ\text{C}/\text{W}$
Thermal Resistance from Junction to Ambient(note2)		70	$^\circ\text{C}/\text{W}$
Junction Temperature	$T_j$	150	$^\circ\text{C}$
Storage Temperature	$T_{stg}$	-55~+150	$^\circ\text{C}$
Lead Temperature for Soldering Purposes(1/8" from case for 10 s)	$T_L$	260	$^\circ\text{C}$

\*Repetitive rating: Please width limited by junction temperature.

Note: 1. When mounted on a minimum pad.

2. When mounted on 1 in<sup>2</sup> of 2oz copper board.

**ELECTRICAL CHARACTERISTICS (T<sub>a</sub>=25°C unless otherwise noted)**

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
<b>STATIC PARAMETERS</b>						
Drain-source breakdown voltage	V <sub>(BR) DSS</sub>	V <sub>GS</sub> = 0V, I <sub>D</sub> = 250μA	20			V
Zero gate voltage drain current	I <sub>DSS</sub>	V <sub>DS</sub> = 16V, V <sub>GS</sub> = 0V			1	μA
Gate-body leakage current	I <sub>GSS</sub>	V <sub>GS</sub> = ±4.5V, V <sub>DS</sub> = 0V			±1	μA
		V <sub>GS</sub> = ±8V, V <sub>DS</sub> = 0V			±10	μA
Gate threshold voltage (note 1)	V <sub>GS(th)</sub>	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 250μA	0.4		1	V
Drain-source on-resistance (note 1)	R <sub>DS(on)</sub>	V <sub>GS</sub> = 10V, I <sub>D</sub> = 7A			20	mΩ
		V <sub>GS</sub> = 4.5V, I <sub>D</sub> = 6.6A			22	mΩ
		V <sub>GS</sub> = 3.8V, I <sub>D</sub> = 6A			24	mΩ
		V <sub>GS</sub> = 2.5V, I <sub>D</sub> = 5.5A			26	mΩ
		V <sub>GS</sub> = 1.8V, I <sub>D</sub> = 5A			35	mΩ
Forward transconductance (note 1)	g <sub>FS</sub>	V <sub>DS</sub> = 5V, I <sub>D</sub> = 7A	9			S
Diode forward voltage(note 1)	V <sub>SD</sub>	I <sub>S</sub> = 1A, V <sub>GS</sub> = 0V			1	V
<b>DYNAMIC PARAMETERS (note 2)</b>						
Input Capacitance	C <sub>iss</sub>	V <sub>DS</sub> = 10V, V <sub>GS</sub> = 0V, f = 1MHz		1150		pF
Output Capacitance	C <sub>oss</sub>			185		pF
Reverse Transfer Capacitance	C <sub>rss</sub>			145		pF
Total gate charge	Q <sub>g</sub>	V <sub>DS</sub> = 10V, V <sub>GS</sub> = 4.5V, I <sub>D</sub> = 7A		15		nC
Gate-source charge	Q <sub>gs</sub>			0.8		nC
Gate-drain charge	Q <sub>gd</sub>			3.2		nC
<b>SWITCHING PARAMETERS(note 2)</b>						
Turn-on delay time	t <sub>d(on)</sub>	V <sub>GS</sub> = 5V, V <sub>DD</sub> = 10V, R <sub>L</sub> = 1.35Ω, R <sub>GEN</sub> = 3Ω		6		ns
Turn-on rise time	t <sub>r</sub>			13		ns
Turn-off delay time	t <sub>d(off)</sub>			52		ns
Turn-off fall time	t <sub>f</sub>			16		ns

**Notes :**

1. Pulse Test : Pulse width≤300μs, duty cycle≤0.5%.
2. Guaranteed by design, not subject to production testing.